

INTERNATIONAL STANDARD

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2001-12

VME64bus – Specification

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CONTENTS

FOREWORD	8
INTRODUCTION	9
1 General	13
1.1 Scope and object	13
1.2 Normative references	13
1.3 VMEbus interface system elements	14
1.4 VMEbus specification diagrams	20
1.5 Specification terminology	22
1.6 Protocol specification	24
1.7 System examples and explanations	25
2 Data transfer bus	25
2.1 Introduction	25
2.2 Data-transfer-bus lines	27
2.3 DTB modules – Basic description	38
2.4 Typical operation	64
2.5 Data-transfer-bus acquisition	73
2.6 DTB timing rules and observations	75
3 Data transfer bus arbitration	120
3.1 Bus arbitration philosophy	120
3.2 Arbitration bus lines	122
3.3 Functional modules	124
3.4 Typical operation	132
3.5 Race conditions between master requests and arbiter grants	141
4 Priority interrupt bus	141
4.1 Introduction	141
4.2 Priority interrupt bus lines	144
4.3 Priority interrupt bus modules – Basic description	146
4.4 Typical operation	159
4.5 Race conditions	165
4.6 Priority interrupt bus timing rules and observations	166
5 Utility bus	183
5.1 Introduction	183
5.2 Utility bus signal lines	183
5.3 Utility bus modules	183
5.4 System initialization and diagnostics	186
5.5 Power and ground pins	190
5.6 Reserved line	191
5.7 Auto slot ID	191
5.8 Auto system controller	198
6 Electrical specifications	199
6.1 Introduction	199
6.2 Power distribution	200
6.3 Electrical signal characteristics	201
6.4 Bus driving and receiving requirements	202

6.5	Backplane signal line interconnections	206
6.6	User defined signals.....	210
6.7	Signal line drivers and terminations	210
7	Mechanical specifications.....	212
7.1	Introduction.....	212
7.2	VMEbus boards.....	213
7.3	Front panels	217
7.4	Backplanes.....	220
7.5	Assembly of VMEbus subracks.....	222
7.6	Conduction cooled VMEbus systems.....	223
7.7	VMEbus backplane connectors and VMEbus board connectors	223
Annex A (normative)	Glossary of VMEbus terms	245
Annex B (normative)	VMEbus Connector/Pin description	251
Annex C (normative)	Manufacturer's board identification	255
Rule index.....		257

iTeh STANDARD PREVIEW

Figure 1 – System elements	(standards.iteh.ai)	15
Figure 2 – Functional modules and buses.....		21
Figure 3 – Signal timing notation	ISO/IEC 15776:2001	25
Figure 4 – Data transfer bus functional block diagram	https://standards.iteh.ai/catalog/standards/sist/68327985-bf35-4f9b-8620-4e21e0cd5315/iso-iec-15776-2001	28
Figure 5 – Block diagram – Master.....		39
Figure 6 – Block diagram – Slave.....		41
Figure 7 – Block diagram – Bus timer		43
Figure 8 – Block diagram – Location monitor		44
Figure 9 – Four ways in which 32 bits of data might be stored in memory.....		53
Figure 10 – Four ways in which 16 bits of data might be stored in memory.....		54
Figure 11 – Block diagram – Configuration ROM / Control & Status registers.....		59
Figure 12 – Example of a non-multiplexed address, single-byte read cycle		66
Figure 13 – Example of multiplexed address double-byte write cycle		67
Figure 14 – Example of non-multiplexed address quad-byte write cycle.....		69
Figure 15 – Example of an eight-byte block read cycle		70
Figure 16 – Data transfer bus master exchange sequence		74
Figure 17 – Address broadcast timing – All cycles		94
Figure 18 – A16, A24, A32 master, responding slave, and location monitor.....		95
Figure 19 – Master, slave, and location monitor – A16, A24 and A32 address broadcast timing		96
Figure 20 – Master, slave, and location monitor A16, A24, and A32 address broadcast timing		97
Figure 21 – Master, slave and location monitor – A64, A40, and ADOH address broadcast timing		98
Figure 22 – Master, slave, and location monitor data transfer timing.....		99
Figure 23 – Master, slave, and location monitor data transfer timing.....		101

Figure 60 – Typical single handler interrupt system operation flow diagram.....	164
Figure 61 – Typical distributed interrupt system with two interrupt handlers, flow diagram.....	165
Figure 62 – Interrupt handler and interrupter – Interrupter selection timing single-byte, double-byte and quad-byte interrupt acknowledge cycles	178
Figure 63 – IACK daisy-chain driver – Interrupter selection timing single-byte, double-byte, and quad-byte interrupt acknowledge cycles.....	178
Figure 64 – Participating interrupter – Interrupter selection timing single-byte, double-byte, and quad-byte interrupt acknowledge cycles.....	179
Figure 65 – Responding interrupter – Interrupter selection timing single-byte, double-byte, and quad-byte interrupt acknowledge cycles.....	179
Figure 66 – Interrupt handler – Status/ID transfer timing single-byte interrupt acknowledge cycle.....	180
Figure 67 – Interrupt handler – Status/ID transfer timing double-byte and quad-byte interrupt acknowledge cycles.....	180
Figure 68 – Responding interrupter – Status/ID transfer timing single-byte interrupt acknowledge cycle.....	181
Figure 69 – Responding interrupter – Status/ID transfer timing double-byte interrupt acknowledge cycle quad-byte interrupt acknowledge cycle	182
Figure 70 – IACK daisy-chain driver, responding interrupter and participating interrupter IACK daisy-chain inter-cycle timing	182
Figure 71 – Utility bus block diagram.....	184
Figure 72 – System clock driver timing.....	185
Figure 73 – Block diagram of power monitor module.....	186
Figure 74 – Power monitor power failure timing.....	187
Figure 75 – Power monitor system restart timing.....	187
Figure 76 – SYSRESET* and SYSFAIL* timing diagram	190
Figure 77 – Current rating for power pins	191
Figure 78 – CR/CSR auto ID slave initialization algorithm	195
Figure 79 – First slot detector (FSD)	198
Figure 80 – VMEbus signal levels	201
Figure 81 – Standard bus termination	208
Figure 82 – Subrack with mixed board sizes.....	226
Figure 83 – Single height board – Basic dimensions.....	227
Figure 84 – Double height board – Basic dimensions	228
Figure 85 – Connector positions on single and double height boards.....	229
Figure 86 – Cross-sectional view of board, connector, backplane, and front panel.....	230
Figure 87 – Optional enhanced DIN connector	231
Figure 88 – Component height, lead length and board warpage.....	232
Figure 89 – Single height, single width front panel.....	233
Figure 90 – Double height, single width front panel.....	234
Figure 91 – Front panel mounting brackets and dimension of single height boards.....	235
Figure 92 – Front panel mounting brackets and dimension of double height boards.....	236
Figure 93 – Single height filler panel	237

Figure 94 – Double height filler panel238

Figure 95 – Backplane detailed dimensions of a J1 and a J2 backplane.....239

Figure 96 – Detailed dimensions of a J1/J2 backplane.....240

Figure 97 – "Off-board type" backplane terminations (viewed from top of backplane)241

Figure 98 – "On-board type" backplane terminations (viewed from top of backplane).....242

Figure 99 – 21 slot subrack243

Figure 100 – Board guide detail.....244

Table 1 – The eight categories of byte locations29

Table 2 – Address alignment on bus29

Table 3 – Signal levels during data transfers used to select which byte location(s) are accessed during a data transfer31

Table 4 – Address modifier codes33

Table 5 – Use of data lines to move data during nonmultiplexed data transfers.....35

Table 6 – Use of the address and data lines for multiplexed data cycles.....36

Table 7 – RULEs and PERMISSIONs specifying the use of the dotted lines by the various types of masters.....40

Table 8 – Slaves – RULEs and PERMISSIONs specifying the use of the dotted lines by the various type of slaves.....42

Table 9 – Use of the BTO() mnemonic specifying the time-out period of bus timers.....43

Table 10 – Location monitors – RULEs and PERMISSIONs specifying the use of the dotted lines by the various types of location monitors.....45

Table 11 – Mnemonics specifying addressing capabilities.....46

Table 12 – Mnemonics specifying basic data transfer capabilities.....48

Table 13 – Mnemonics specifying block transfer capabilities.....51

Table 14 – The mnemonic that specifies read-modify-write capabilities52

Table 15 – Transferring 32 bits of data using multiple-byte transfer cycles54

Table 16 – Transferring 16 bits of data using multiple-byte transfer cycles55

Table 17 – Mnemonic that specifies unaligned transfer capability55

Table 18 – Mnemonics specifying address only capability56

Table 19 – Configuration ROM/control & status registers: RULEs and PERMISSIONs or monitoring the dashed lines.....60

Table 20 – Control and status register base definition60

Table 21 – Configuration ROM definition.....61

Table 22 – Timing diagrams defining master, slave, and location monitor operation (see Table 27 for timing values)76

Table 23 – Definitions of mnemonics used in Tables 24, 25 and 26.....78

Table 24 – Use of the address and data lines to select a byte group.....78

Table 25 – Use of DS1*, DS0*, A1, A2, and LWORD* during the address phase of the various cycles.....79

Table 26 – Use of the data lines to transfer data.....80

Table 27 – Master, slave, and location monitor timing parameters	83
Table 28 – Bus-timer timing parameters (see also Table 32)	84
Table 29 – Master, timing RULEs and OBSERVATIONS	84
Table 30 – Slave, timing RULEs and OBSERVATIONS	89
Table 31 – Location monitor, timing OBSERVATIONS	93
Table 32 – BUS TIMER, timing RULEs	94
Table 33 – RULEs and PERMISSIONs specifying the use of the dotted lines by the various types of arbiters	128
Table 34 – RULEs and PERMISSIONs specifying the use of the dotted lines by the various types of requesters	131
Table 35 – RULEs and PERMISSIONs specifying the use of the dotted lines in Figure 51 by the various types of interrupt handlers	149
Table 36 – RULEs and PERMISSIONs specifying the use of the dotted lines in Figure 52 by the various types of interrupters	151
Table 37 – Use of the IH() mnemonic to specify interrupt request handling capabilities	153
Table 38 – Use of the I() mnemonic to specify interrupt request generation capabilities	153
Table 39 – Mnemonics specifying status/ID transfer capabilities	153
Table 40 – Mnemonics specifying interrupt request release capabilities	155
Table 41 – 3-bit interrupt acknowledge code	164
Table 42 – Timing diagrams defining interrupt handler and interrupter operation	167
Table 43 – Timing diagrams defining IACK daisy-chain driver operation	168
Table 44 – Timing diagrams defining participating interrupter operation	168
Table 45 – Timing diagrams that define responding interrupter operation	168
Table 46 – Definitions of mnemonics used in tables 47, 48 and 49	169
Table 47 – Use of addressing lines during interrupt acknowledge cycles	169
Table 48 – Use of the DS1*, DS0*, LWORD* and WRITE* lines during interrupt acknowledge cycles	170
Table 49 – Use of the data bus lines to transfer the Status/ID	170
Table 50 – Interrupt handler, interrupter and IACK daisy-chain driver timing parameters	171
Table 51 – Interrupt handler, timing RULEs and OBSERVATIONS	172
Table 52 – Interrupter, timing RULEs and OBSERVATIONS	174
Table 53 – IACK daisy-chain driver, timing RULEs and OBSERVATIONS	177
Table 54 – Module drive during power-up and power-down sequences	189
Table 55 – Bus voltage specification	200
Table 56 – Bus driving and receiving requirements	202
Table 57 – Bus driver summary	211
Table 58 – J1/P1 pin assignments	224
Table 59 – J2/P2 pin assignments	225

VME64bus – SPECIFICATION

FOREWORD

- 1) ISO (the International Organization for Standardization) and IEC (the International Electrotechnical Commission) form the specialized system for worldwide standardization. National bodies that are members of ISO or IEC participate in the development of International Standards through technical committees established by the respective organization to deal with particular fields of technical activity. ISO and IEC technical committees collaborate in fields of mutual interest. Other international organizations, governmental and non-governmental, in liaison with ISO and IEC, also take part in the work.
- 2) In the field of information technology, ISO and IEC have established a joint technical committee, ISO/IEC JTC1. Draft International Standards adopted by the joint technical committee are circulated to national bodies for voting. Publication as an International Standard requires approval by at least 75 % of the national bodies casting a vote.
- 3) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. ISO and IEC shall not be held responsible for identifying any or all such patent rights.

International Standard ISO/IEC 15776 was prepared by subcommittee 26: Microprocessor systems, of ISO/IEC joint technical committee 1: Information technology.

International Standards are drafted in accordance with ISO/IEC Directives, Part 3.

Annexes A, B and C form an integral part of this International Standard.

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INTRODUCTION

The architectural concepts of VMEbus are based on the VERSAbus developed by Motorola in the late 1970s. Motorola's European Microsystems group in Munich, West Germany proposed the development of a VERSAbus-like product line of computers and controllers based on the Eurocard mechanical standard. To demonstrate the concept, Max Loesel and Sven Rau developed three prototype boards: (1) a 68000 CPU card, (2) a dynamic memory card, and (3) a static memory card. They named the new bus VERSAbus-E, which was later renamed "VME" by Lyman Hevle, then VP of the Motorola Microsystems Operation (and later the founder of VITA). VME is the acronym for VERSA-module Europe. Motorola, Mostek, and Signetics agreed to jointly develop and support the new bus architecture in early 1981.

John Black of Motorola, Craig McKenna of Mostek, and Cecil Kaplinsky of Signetics developed the first draft of the VMEbus specification. In October of 1981, at the Systems 81 trade show in Munich, West Germany, Motorola, Mostek, and Signetics announced their joint support for VMEbus, and placed Revision A of the specification in the public domain.

In August of 1982, Revision B of the VMEbus specification was published by the newly formed VMEbus Manufacturers Group (now VITA). This new revision refined the electrical specifications for the signal line drivers and receivers, and also brought the mechanical specifications more in line with the developing IEC 60297 standard, the formal specifications for Eurocard mechanical formats.

In the latter part of 1982, the French delegation of the International Electrotechnical Commission (IEC) proposed Revision B of the VMEbus specification as an international standard. The IEC SC47B subcommittee nominated Mira Pauker of Philips, France as the chairperson of an editorial committee, formally starting international standardization of the VMEbus.

In March of 1983, the IEEE Microprocessor Standards Committee (MSC) requested authorization to establish a working group to standardize the VMEbus in the US. This request was approved by the IEEE Standards Board, and the P1014 Working Group was established. Wayne Fischer was appointed first chairman of the working group. John Black served as chairman of the P1014 Technical Subcommittee.

The IEC, IEEE, and VMEbus Manufacturers Group (now VITA) distributed copies of Revision B for comment, and received requests for changes to the document as a result. These comments made it clear that it was time to go forward past revision B. In December of 1983, a meeting was held that included John Black, Mira Pauker, Wayne Fischer, and Craig McKenna. It was agreed that a revision C should be created, and that it should take into consideration all comments received by the three organizations. John Black and Shlomo Pri-Tal of Motorola incorporated the changes from all sources into a common document. The VMEbus Manufacturers Group (now VITA) labeled the document Revision C.1 and placed it in the public domain. The IEEE labeled it P1014 Draft 1.2, and the IEC labeled it IEC 60821 Bus. Subsequent ballots in the IEEE P1014 group and in the MSC resulted in more comments, and required that the IEEE P1014 draft be updated. This work resulted in the ANSI/IEEE 1014-1987 specification.

In 1989, John Peters of Performance Technologies, Inc. (Rochester, NY) developed the initial concept of VME64: multiplexing address and data lines (A64/D64) on the VMEbus. This concept was shown for the first time in 1989 and placed in the VITA Technical Committee in 1990 as a performance enhancement to the VMEbus specification. In 1991, the PAR (Project Authorization Request) for P1014R (revisions to the VMEbus specification) was granted by the IEEE. Ray Alderman, Technical Director of VITA, co-chaired the activity with Kim Clohessy of DY 4 Systems (Nepean, Ontario, Canada).

At the end of 1992, the additional enhancements to VMEbus (A40/D32, Locked Cycles, Rescinding DTACK*, Autoslot-ID, Auto System Controller, and enhanced DIN connector mechanicals) required more work to complete this document. In 1992, the VITA Technical Committee suspended work with the IEEE and sought accreditation as a standards developer organization (SDO) with the American National Standards Institute. The original IEEE Par P1014R was subsequently withdrawn by the IEEE. The VITA Technical Committee returned to using the public domain VMEbus C.1 specification as its base level document to which it added new enhancements. This enhancement work was undertaken entirely by the VITA Technical Committee resulting in this document. The tremendous undertaking of the document editing was accomplished by Kim Clohessy of DY 4 Systems, the technical co-chair of the activity with great help from Frank Hom who created the mechanical drawings, and with exceptional contributions by each chapter editor.

Additional enhancements proposed to the VME64 Subcommittee have been placed in another VITA subcommittee: the VME64 Extensions Document. Two other activities began in late 1992: (1) BLLI (VMEbus Board-level Live Insertion Specifications), and (2) VSLI (VMEbus System-level Live Insertion with Fault Tolerance).

New activities begun in 1993 using the base-VME architecture involve the implementation of high-speed serial and parallel sub-buses for use as I/O interconnections and data mover subsystems. These architectures can be used as message switches, routers, and small multiprocessor parallel architectures.

VITA's application for recognition as an accredited standards developer organization of ANSI (American National Standards Institute) was granted in June 1993. Numerous other documents, including mezzanine, P2, and serial bus standards, have been placed with VITA as the Public Domain Administrator of these technologies.

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VMEbus Specification Genealogy

VMEbus	Revision B and C.1 (Public Domain) ⁰¹
IEEE 1014-1987	Versatile Backplane Bus VMEbus <small>http://standards.iteh.ai/catalog/standards/sist/68327985-bf35-4f9b-8620-4c21c0cd5315/iso-iec-15776-2001</small>
VITA 1-1994	VME64 Specification
IEEE 1096-1988	VSBBus Specification (IEEE)
IEC 60821:1991	VMEbus – Microprocessor system bus for 1 byte to 4 byte data
IEEE 1101.1	IEEE Standard for Mechanical Core Specifications for Microcomputers Using IEC 60603-2 Connectors
IEEE 1101.2	IEEE Standard for Mechanical Core Specification for Conduction-Cooled Eurocards

This standard was constructed through the many hours of hard work by the members of the VME64 Subcommittee (of the VITA Technical Committee) and the commitment of their companies to this standard.

NAME	COMPANY
Ray Alderman	PEP Modular Computers
Michael Humphrey	VITA
John Rynearson	VITA
Martin Blake	BICC-VERO UK
Kim Clohessy	DY 4 Systems, Inc.
Jing Kwok	DY 4 Systems, Inc.
Clarence Peckham	Heurikon Corporation
Dennis Terry	Heurikon Corporation
Wayne Fischer	Force Computers Inc.
Jack Regula	Consultant
Tad Kubic	Dawn VME Products, Inc.
Will Hamsher	AMP, Inc.
Doug Reubendall	AMP, Inc.
William Mahusen	Performance Technologies, Inc.
Thanos Mentzelopoulos	Ironics, Inc.
Joel Silverman	Radstone Technology Corp.
Colin Davies	Radstone Technology UK
Frank Hom	Electronic Solutions
Keith Burgess	Mizar
John Black	Micrology PBT
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Sam Babb	Hewlett Packard Co.
Ben LaPointe	Motorola GEG
Chau Pham	Motorola MCG
Mac Rush	Motorola MCG
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Eike Waltz	Schroff, Inc.
Tom Baillio	Mercury Computer Systems, Inc.
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Dave Horton	Cypress Semiconductor
Mike Maas	Cypress Semiconductor
Mike Munroe	Hybricon Corp.

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Kim Clohessy	DY-4 Systems Inc.
Wayne Fischer	Force Computers, Inc.
Chau Pham	Motorola MCG
Frank Hom	Electronic Solutions
Richard DeBock	Matrix Corp.
Jing Kwok	DY 4 Systems, Inc.
Mike Hasenfratz	Micro Memory, Inc.

CANVASS BALLOT

Consensus for this standard was achieved by use of the Canvass Method.

The following organizations, recognized as having an interest in the standardization of VME64, participated in the Canvass Ballot process. Inclusion in this list does not necessarily imply that the organization concurred with the submittal of the proposed standard to ANSI.

767 AWACS	Micrology
Adept Technology	MITRE Corporation
AMP	Motorola Computer Group
AT&T Bell Laboratories	Mupac Corporation
Berg Electronics	Newbridge Microsystems
Bit 3 Computer	Object Technology Inc.
CERN	PEP Modular Computers
CSPI	Philips Ind. Automation
Cypress Semiconductor	Picosoft
Dawn VME Products	Radstone Technology
Dialogic Corporation	Schroff
Digital Equipment Corp.	Technology Consulting
DY 4 Systems	Texas Instruments
Electronic Solutions	VERO Electronics
Force Computers	VITA
Harting Elektronik	VME MEMBER
Heurikon Corporation	Winchester Electronics
Hewlett-Packard	
Hughes Aircraft Company	
Hybricon Corporation	
IBM	
IXTHOS	
Loral Western Devel. Lab	
Los Alamos Nat'l Lab	
Matrix Corporation	
Micro Memory	

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VME64bus – SPECIFICATION

1 General

1.1 Scope and object

The VMEbus specification defines an interfacing system used to interconnect microprocessors, data storage, and peripheral control devices in a closely coupled hardware configuration. The system has been conceived with the following objectives:

- a) to allow communication between devices on the VMEbus without disturbing the internal activities of other devices interfaced to the VMEbus;
- b) to specify the electrical and mechanical system characteristics required to design devices that will reliably and unambiguously communicate with other devices interfaced to the VMEbus;
- c) to specify protocols that precisely define the interaction between the VMEbus and devices interfaced to it;
- d) to provide terminology and definitions that describe the system protocol;
- e) to allow a broad range of design latitude so that the designer can optimize cost and/or performance without affecting system compatibility;
- f) to provide a system where performance is primarily device limited, rather than system interface limited.

1.2 Normative references

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The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60297-1:1986, *Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 1: Panels and racks*

IEC 60297-2:1982, *Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 2: Cabinets and pitches of rack structures*

IEC 60297-3:1984, *Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3: Subracks and associated plug-in units*

IEC 60297-4:1995, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 4: Subracks and associated plug-in units – Additional dimensions*

IEC 60603-2:1995, *Connectors for frequencies below 3 MHz for use with printed boards – Part 2: Detail specification for two-part connectors with assessed quality, for printed boards, for basic grid of 2.54 mm (0.1 in) with common mounting features*

IEC 61076 (all parts), *Connectors with assessed quality, for use in d.c., low frequency analogue and digital high speed data applications*

IEEE 1101.2, *Standard for Mechanical Core Specifications for Conduction-Cooled Eurocards*

IEEE 1394, *Standard for a High Performance Serial Bus*